

FIG.1A

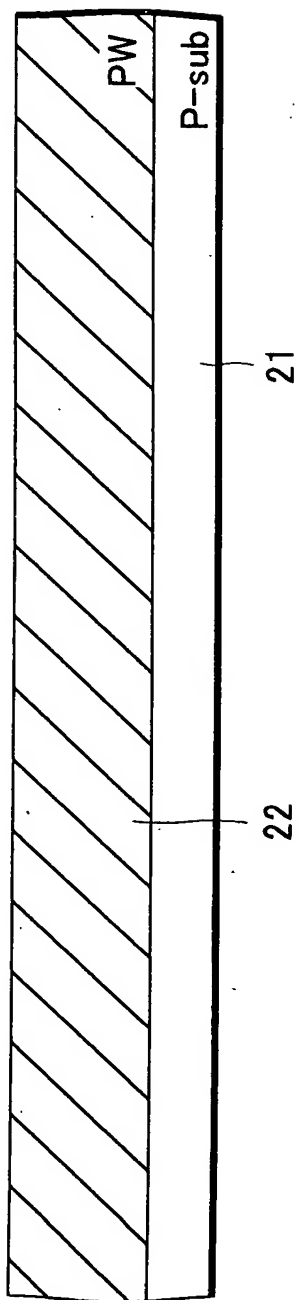


FIG.1B

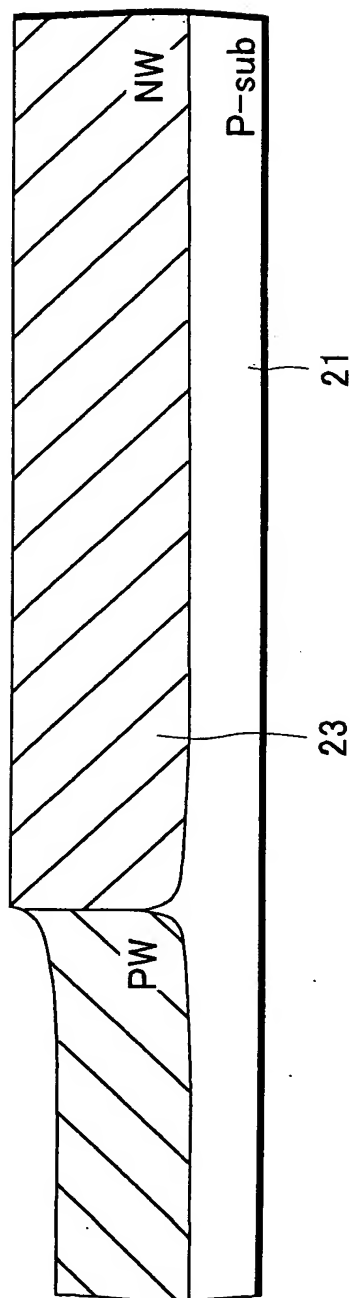
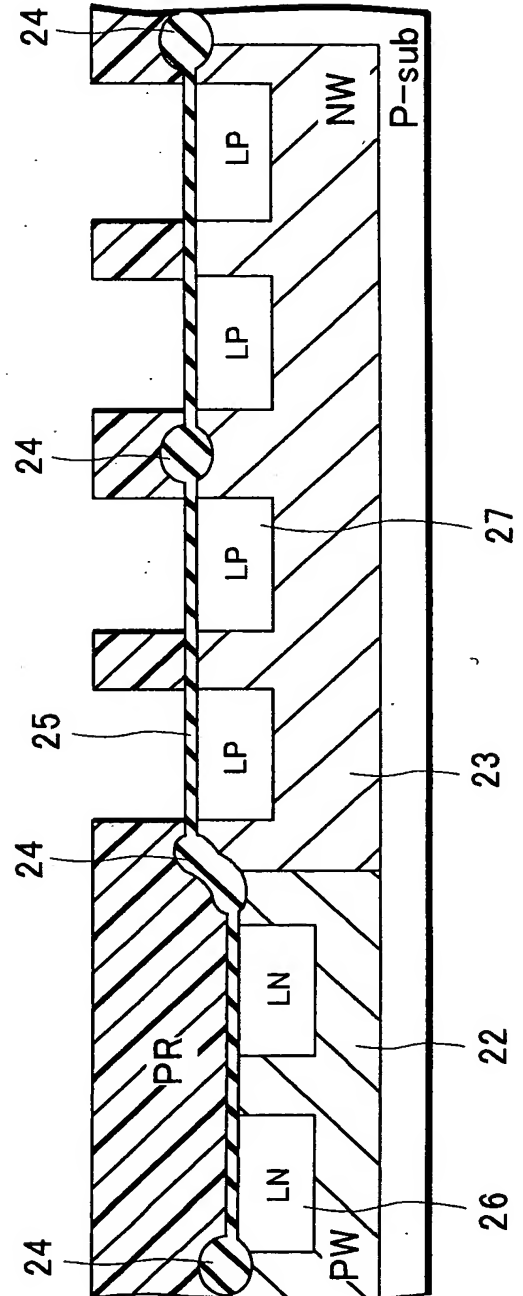


FIG. 2B



This cross-sectional view shows a semiconductor device on a P-substrate. The device features a series of regions labeled 22, 23, 24, 25, 26, 27, 28, and 29. Layer 24 is a top layer with openings. Layer 25 is a middle layer. Layer 26 is a bottom layer. Layer 27 is a top layer. Layer 28 is a middle layer. Layer 29 is a bottom layer. The device includes a P-substrate, a P-substrate, a P-substrate, a P-substrate, a P-substrate, a P-substrate, a P-substrate, and a P-substrate. Other labels include LP, LN, PW, NW, and PR.

FIG. 4A

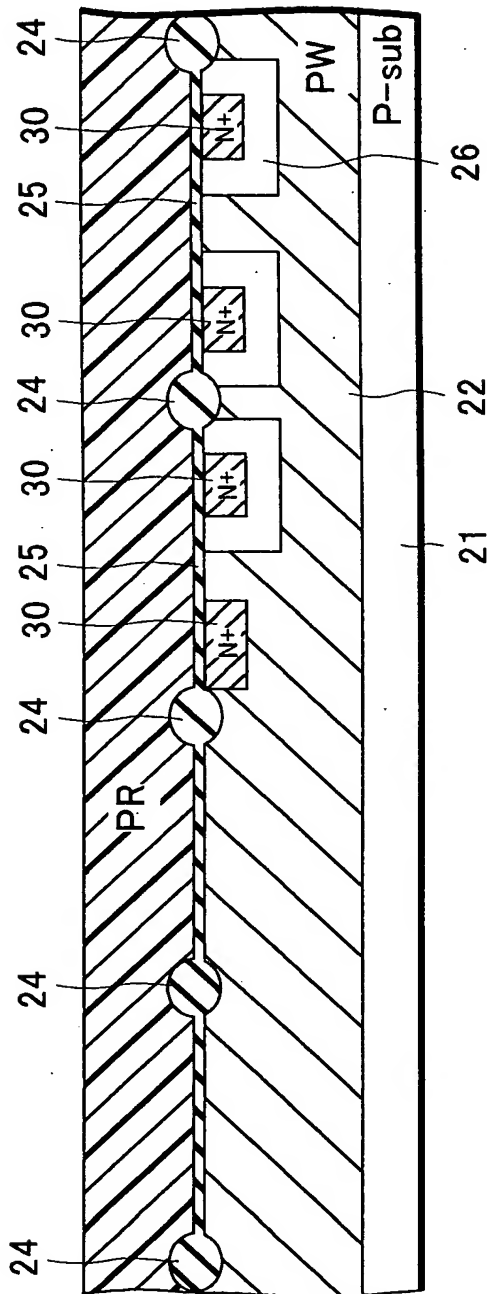


FIG. 4B

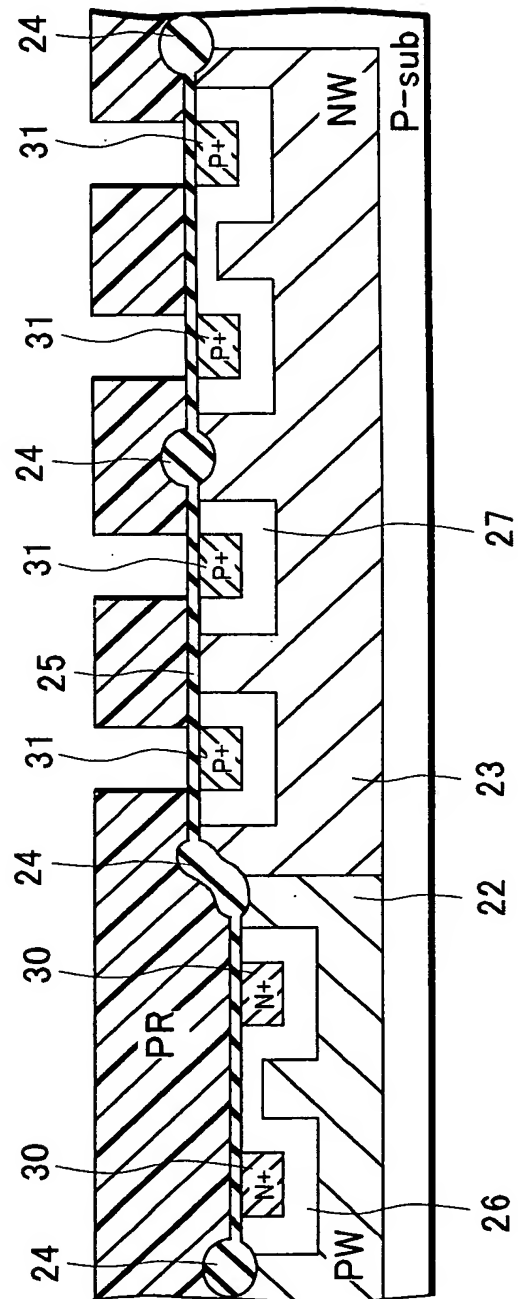


FIG.5A

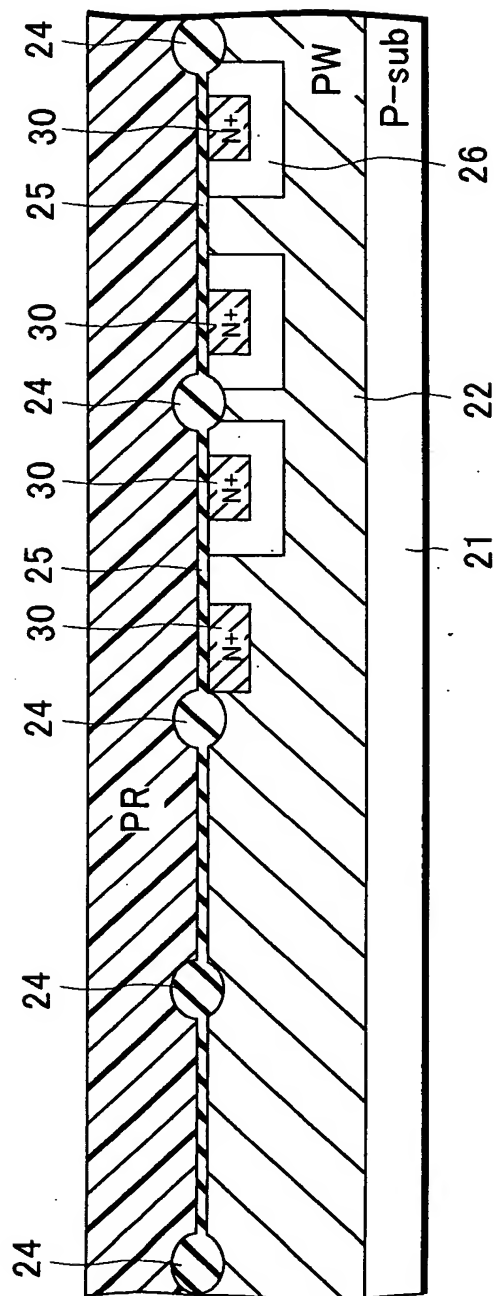


FIG.5B

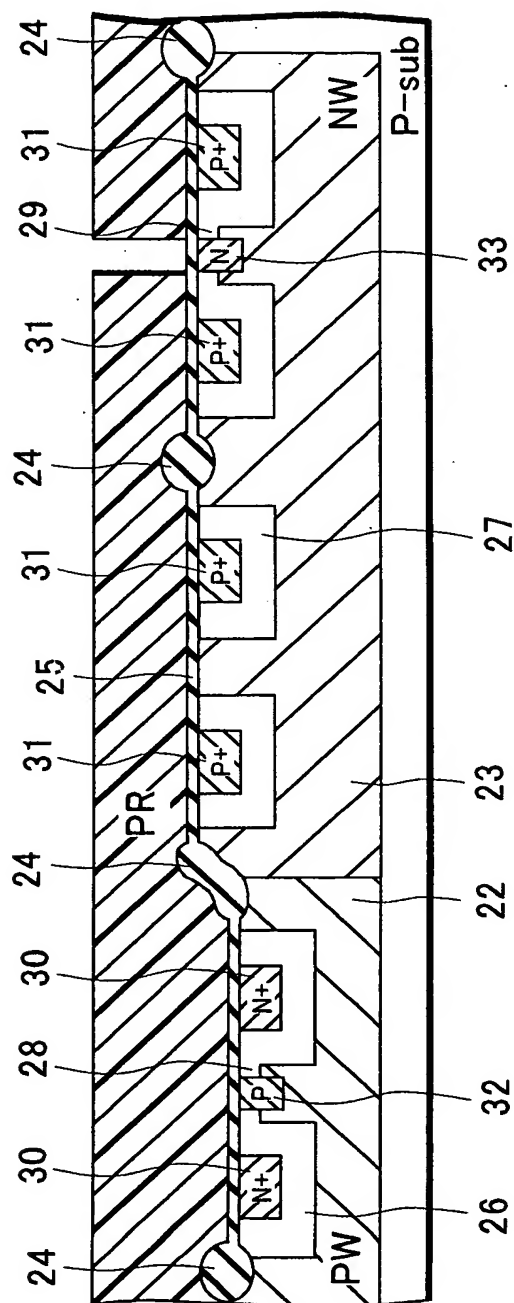


FIG. 6B

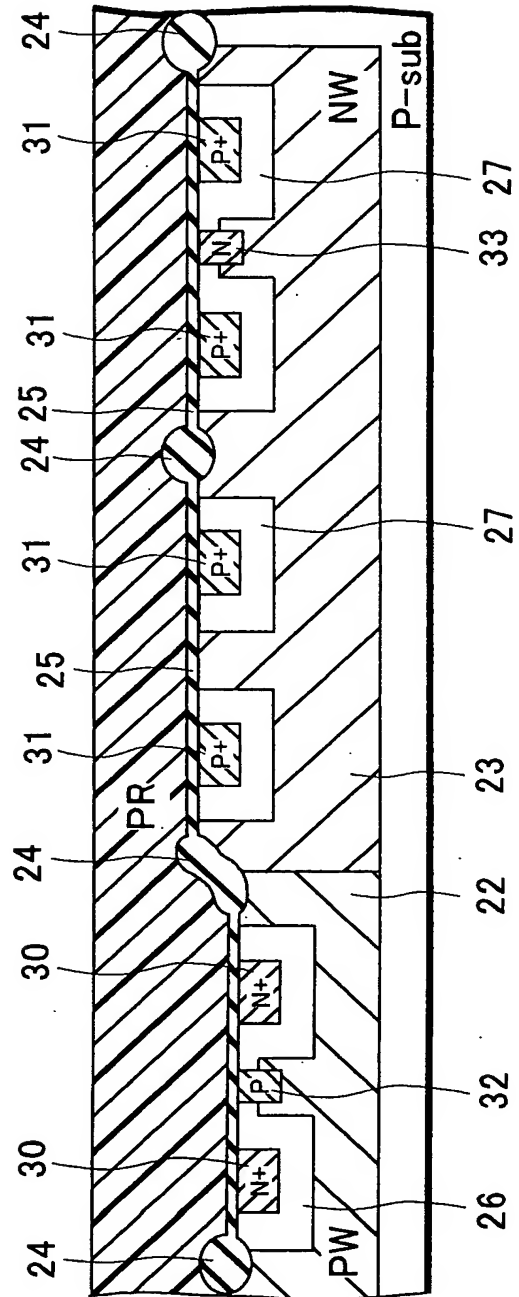


FIG. 7A

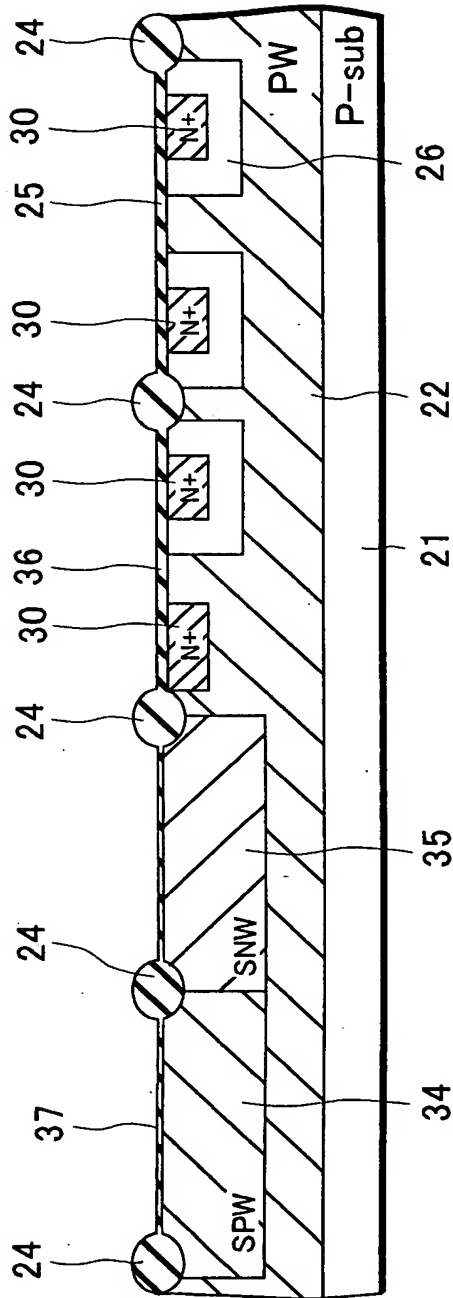


FIG. 7B

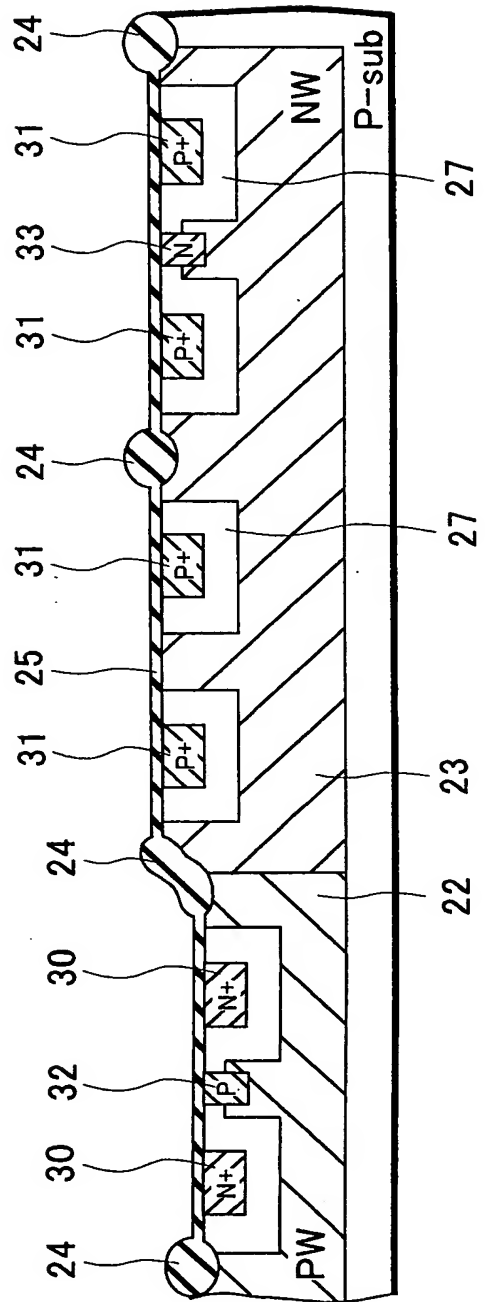


FIG.8A

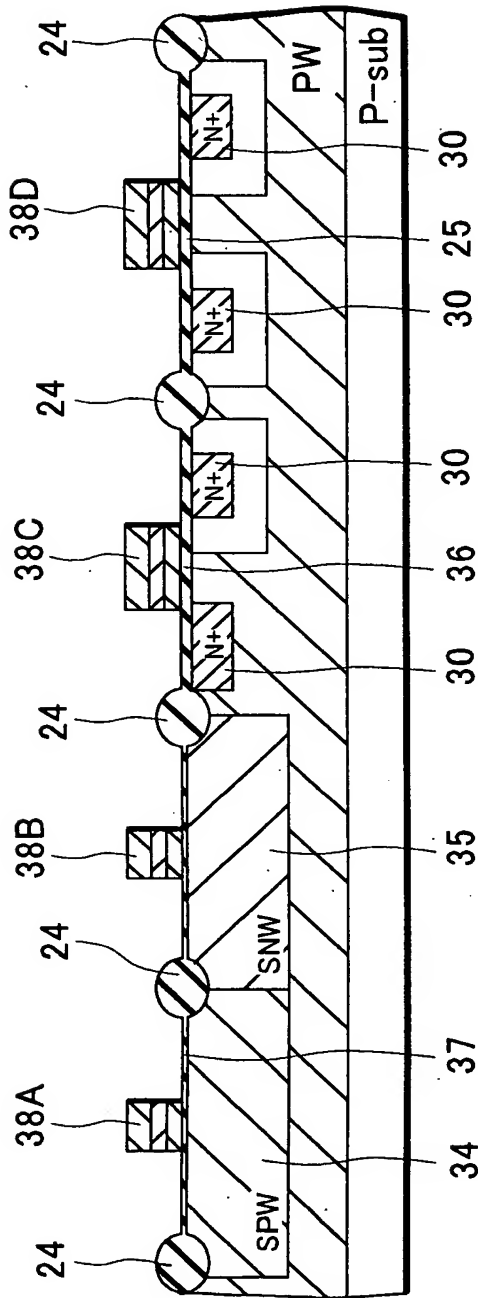


FIG.8B

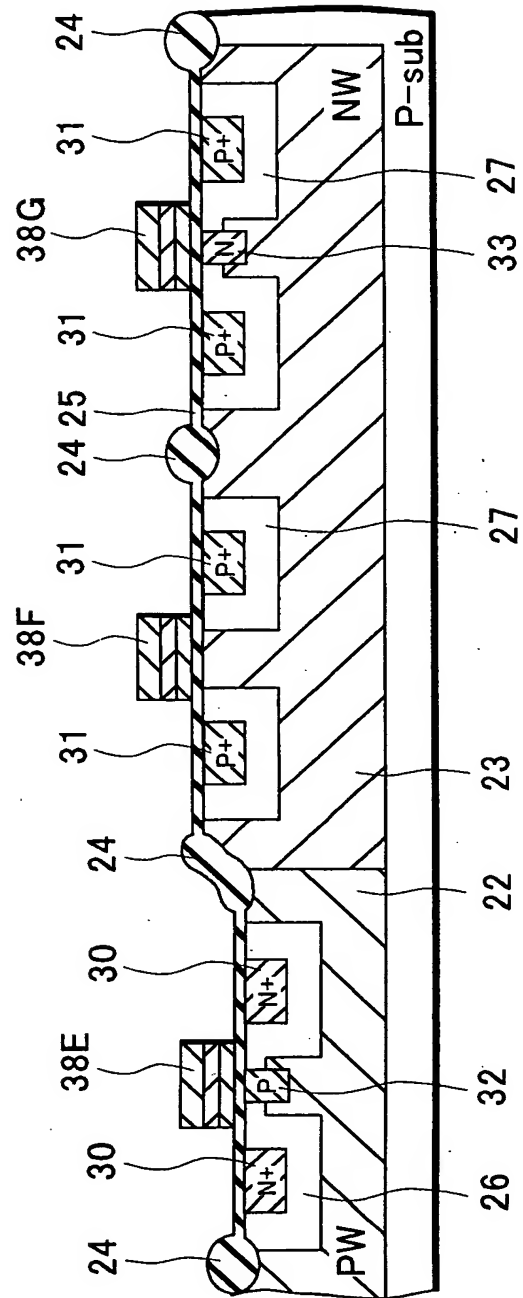


FIG.9A

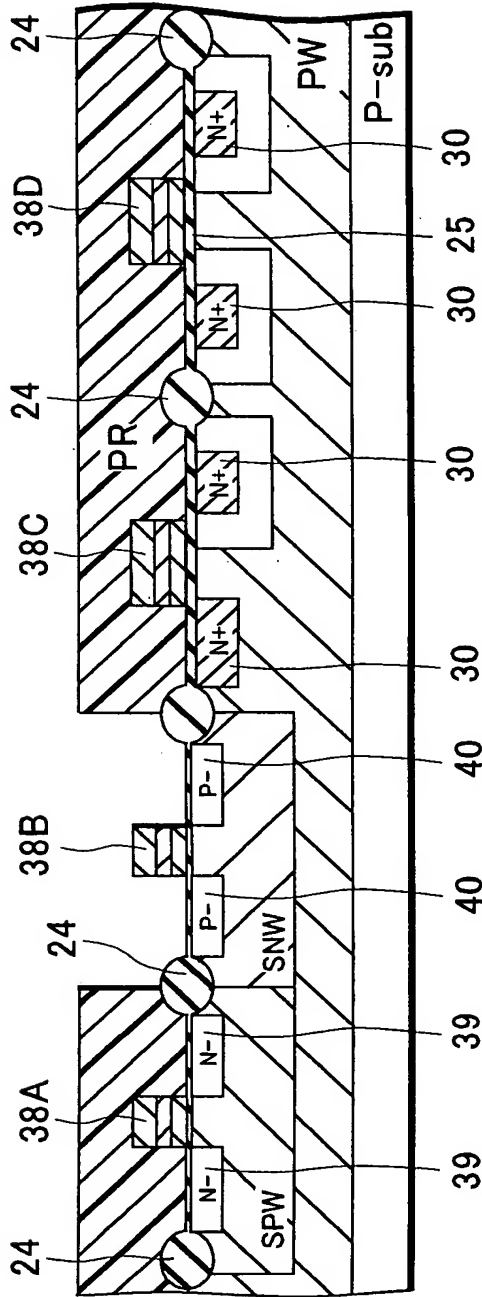


FIG.9B

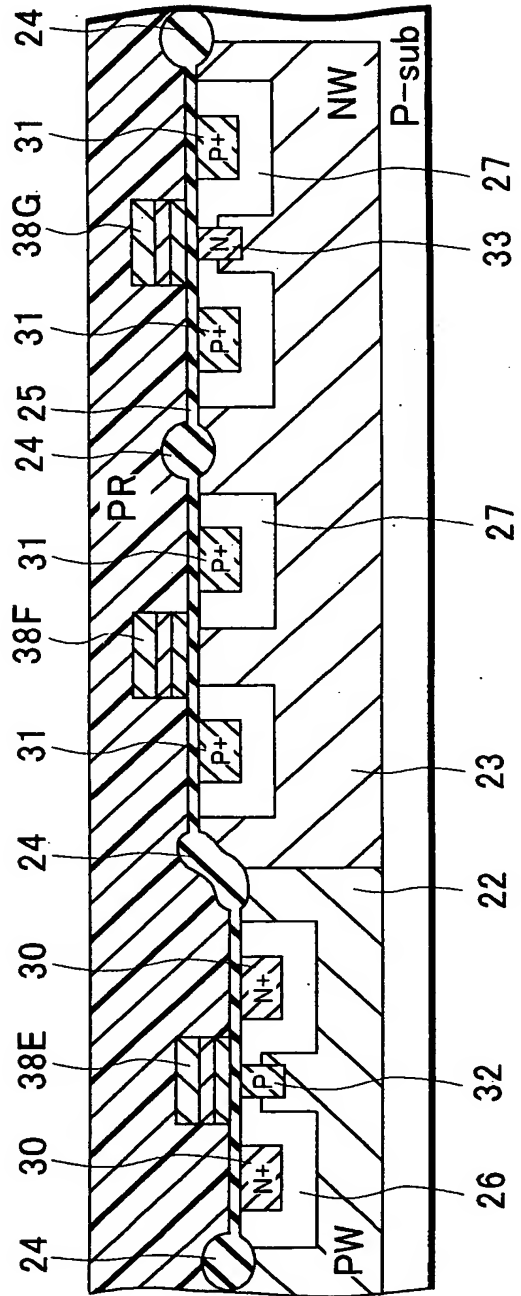


FIG.10A

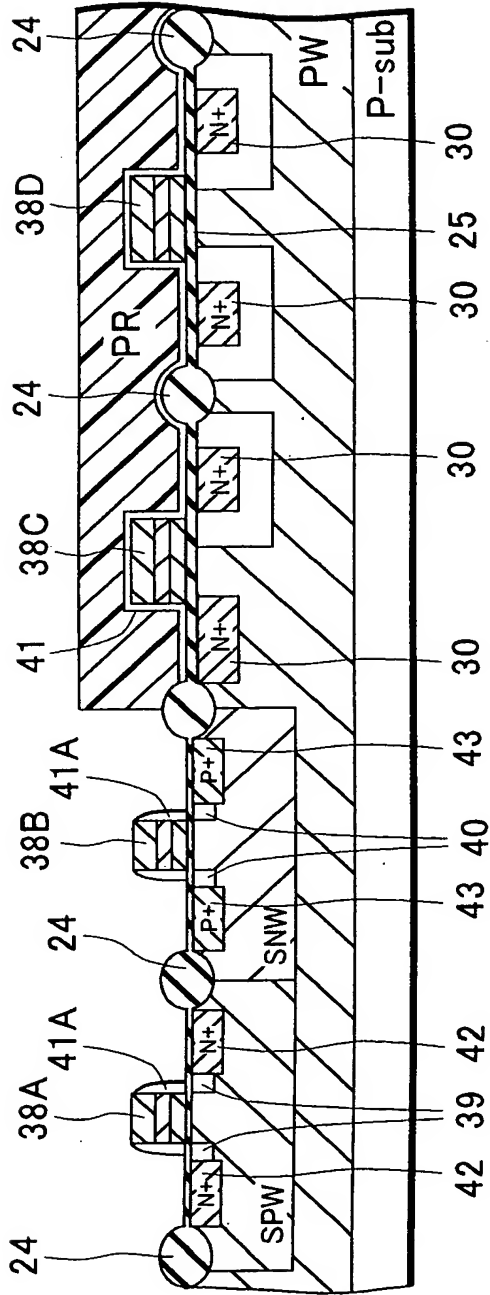


FIG.10B

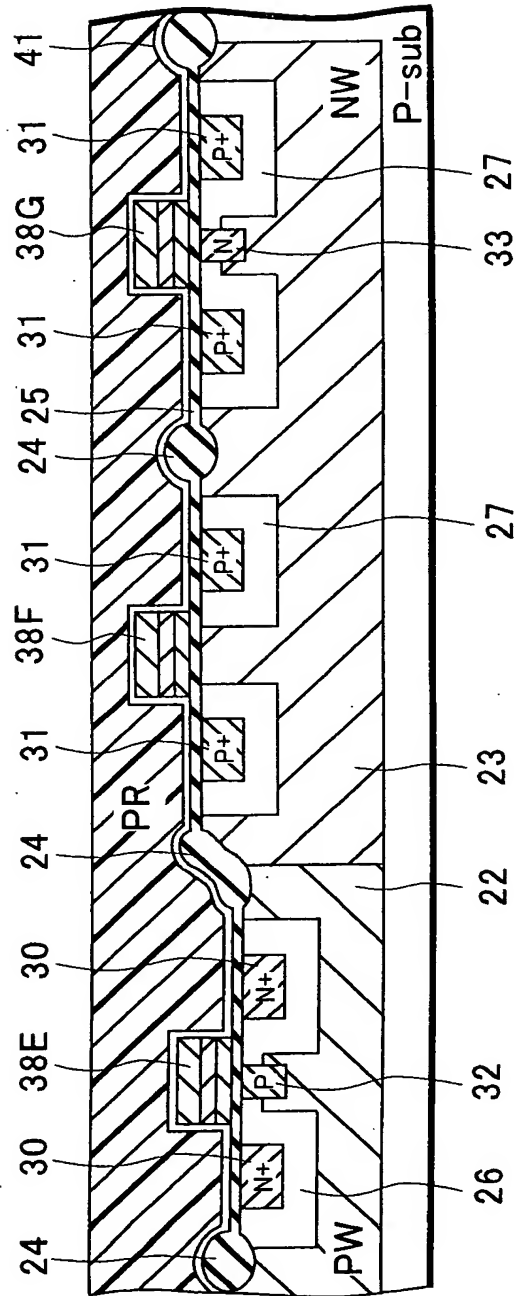


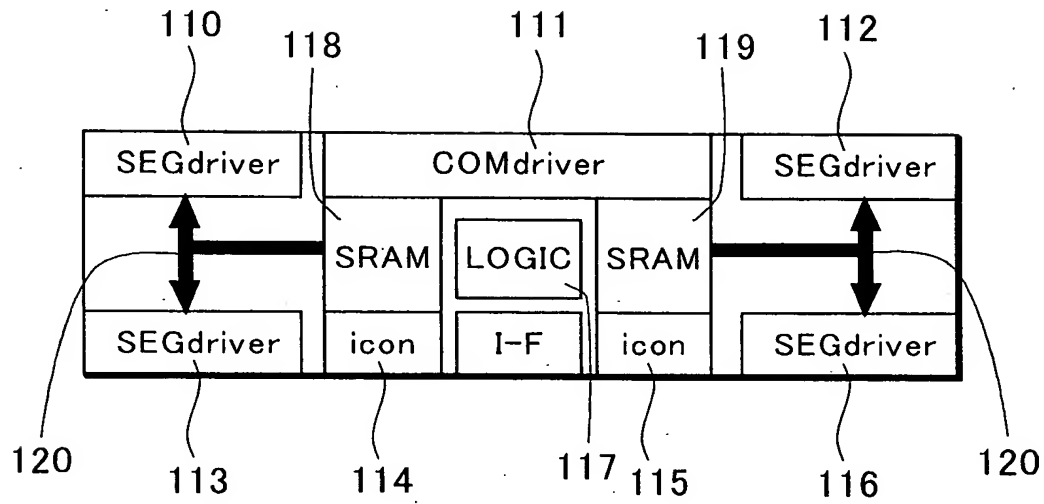
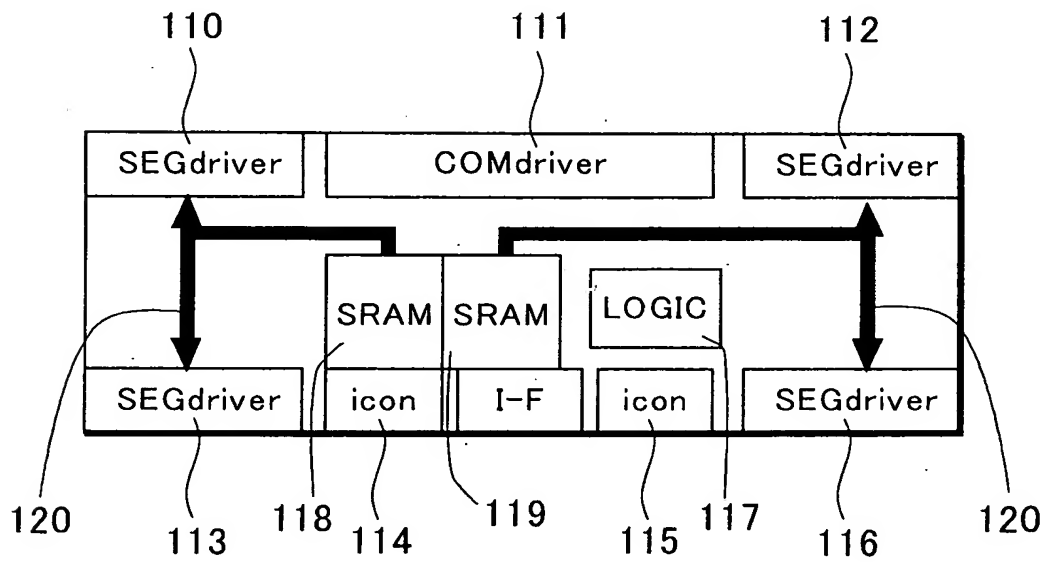
FIG.11A**FIG.11B**

FIG. 12

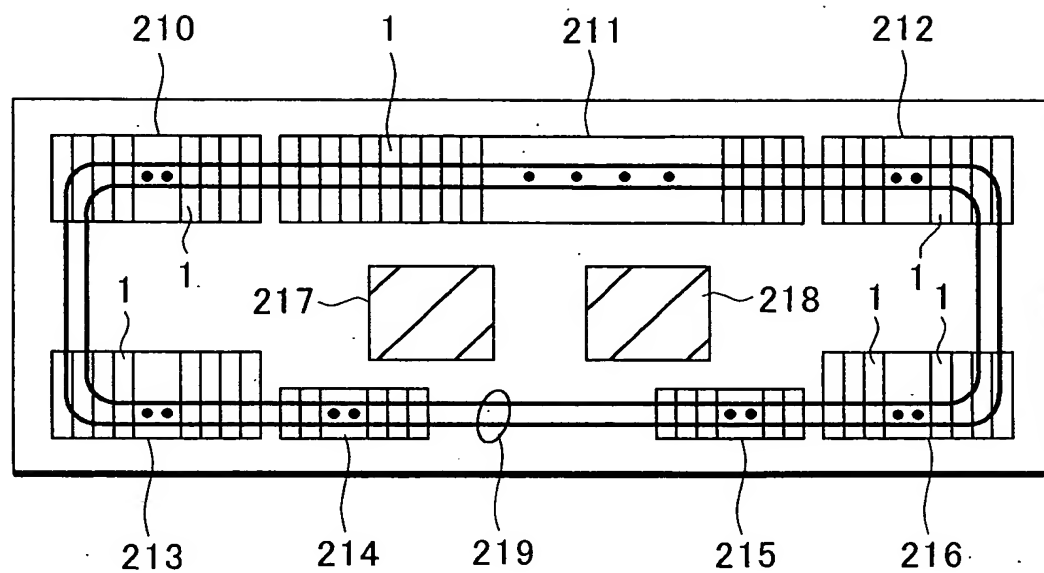


FIG. 13

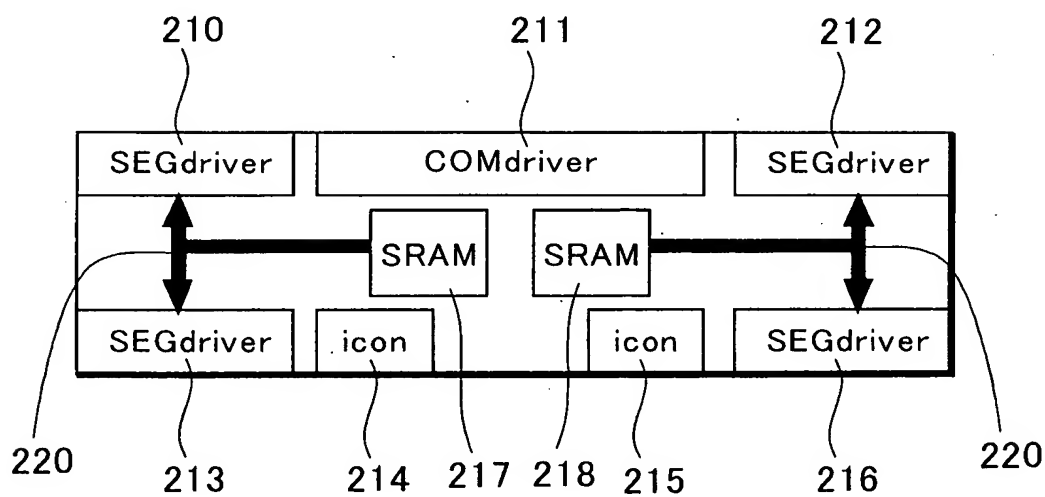


FIG. 14A

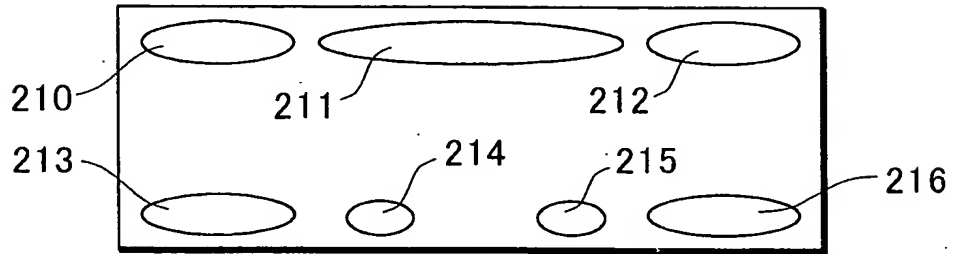


FIG. 14B

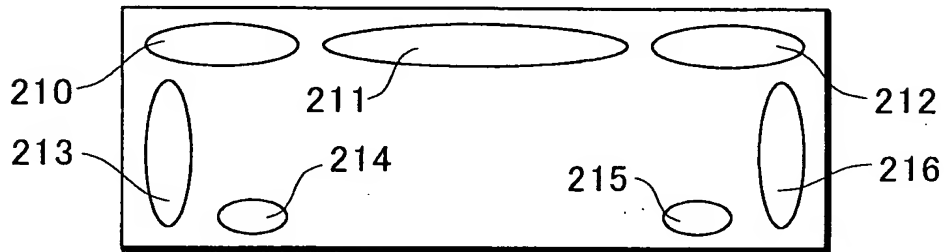


FIG. 14C

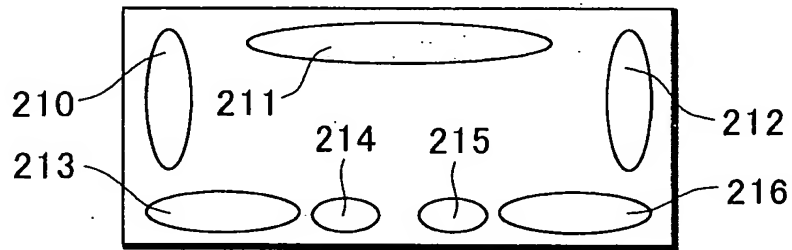


FIG. 14D

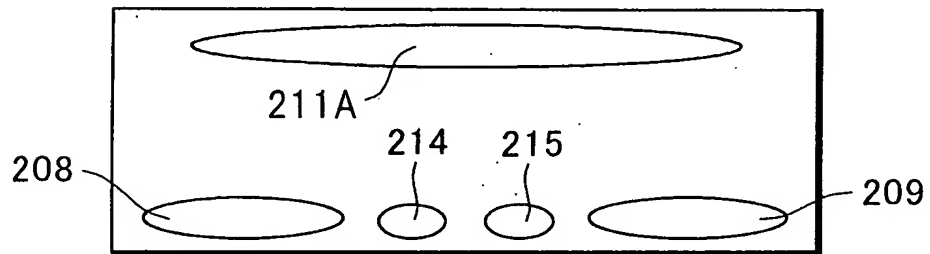


FIG. 16

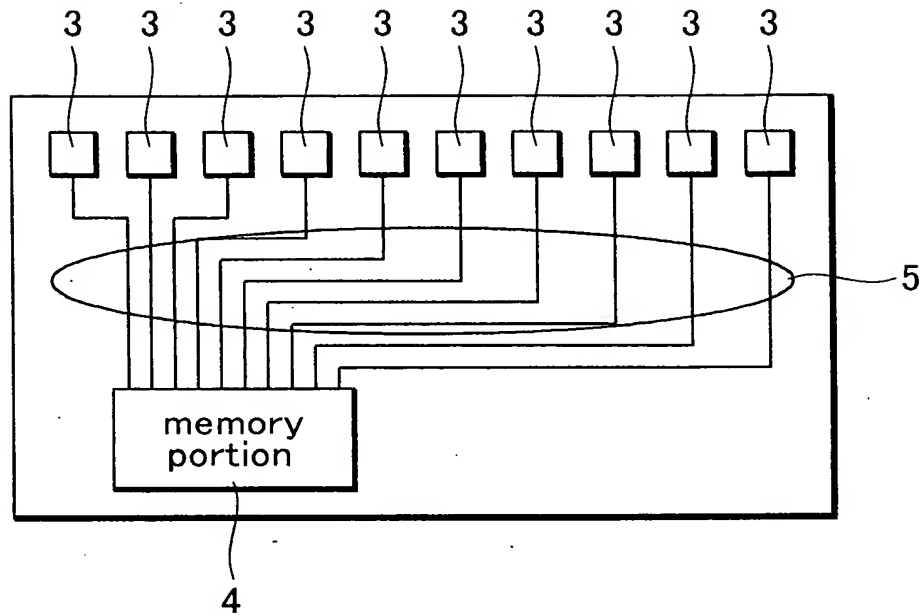


FIG.17A

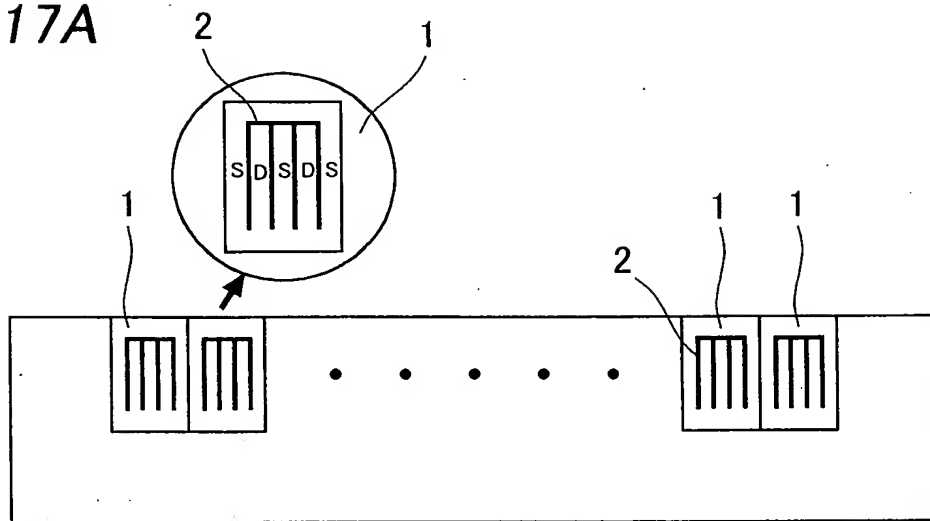


FIG.17B

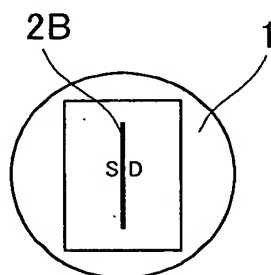


FIG.17C

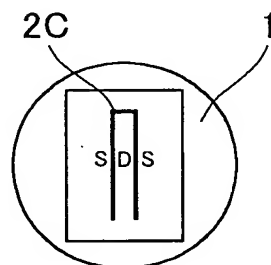


FIG.17D

